



## Material Content Data Sheet



Sales Product Name	TLE4963-1M			Issued		11. December 2019		
MA#	MA004069644							
Package	PG-SOT23-3-15			Weight*		9.82 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.302	3.08	3.08	30799	30799
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		73	
	non noble metal	titanium	7440-32-6	0.004	0.04		367	
	non noble metal	chromium	7440-47-3	0.011	0.11		1101	
	non noble metal	copper	7440-50-8	3.590	36.55	36.71	365540	367081
wire	noble metal	gold	7440-57-5	0.023	0.23	0.23	2303	2303
encapsulation	organic material	carbon black	1333-86-4	0.054	0.55		5493	
	plastics	epoxy resin	-	1.160	11.81		118097	
	inorganic material	silicondioxide	60676-86-0	4.180	42.58	54.94	425700	549290
leadfinish	non noble metal	tin	7440-31-5	0.150	1.52	1.52	15238	15238
plating	noble metal	silver	7440-22-4	0.149	1.51	1.51	15130	15130
glue	plastics	epoxy resin	-	0.035	0.35		3528	
	noble metal	silver	7440-22-4	0.163	1.66	2.01	16631	20159
*deviation	< 10%	Sum in total:			100.00		1000000	

### Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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